case with the technology described in patent document 1, there is a problem that maintenance replacement work cannot be performed for each individual piece of electronic substrate housing equipment.

~~The present invention has been made in view of such circumstances, and an object~~ Embodiments of the present invention ~~is to~~ provide electronic substrate housing equipment and electronic apparatus which settle the problem that maintenance replacement work cannot be performed for each individual piece of electronic substrate housing equipment if it is tried to cool electronic substrate housing equipment efficiently.

Means for Solving the Problems

According to a first aspect of the present invention, there is provided an ~~Electronic~~electronic substrate housing equipment comprising ~~of the present invention has~~: an electronic substrate to mount a healer element; a chassis to house the electronic substrate in an airtight manner; a cooling unit to cool the electronic substrate; and the cooling unit including: a heat receiving part to receive heat from the electronic substrate; a heat radiation part, connected with the heat receiving part, to radiate heat received by the heat receiving part; and the heat receiving part being provided in the chassis in an airtight manner, and the heat radiation part being provided outside the chassis.

According to a second aspect of the present invention, there is provided an ~~Electronic~~electronic apparatus ~~of the present invention has~~comprising: electronic substrate housing equipment and a rack to house the electronic substrate housing equipment, wherein the electronic substrate housing equipment includes: an electronic substrate to mount a heater element; a chassis to house the electronic substrate in an airtight manner; and a cooling unit, wherein the cooling unit includes: a heat receiving part to receive heat from the electronic substrate; and a heat radiation part, connected with the heat receiving part, to radiate heat received by the heat receiving part; and wherein the heat receiving part is provided in the chassis in an airtight manner, and the heat radiation part is provided outside the chassis.

Advantage of the Invention

According to electronic substrate housing equipment and electronic apparatus according to embodiments of the present invention, efficient cooling is possible, and moreover, maintenance replacement work can be performed for each electronic substrate housing equipment individually.

Brief Description of the Drawings

[Fig- 1]

Fig. 1 is a side face perspective view showing a structure of electronic substrate housing equipment in a first exemplary embodiment of the present invention seen through from a side.

[Fig. 2]

Fig. 2 is a surface perspective view seen from cutting plane A-A of Fig. 1.

[Fig. 3]

Fig. 3 is a side face perspective view seen from cutting plane B-B of Fig. 2.

[Fig- 4]

Fig. 4 is a side face perspective view seen from cutting plane C-C of Fig. 2.

[Fig. 5]

Fig. 5 is a perspective view showing a structure of a cooling unit.

[Fig. 6]

Fig. 6 is a perspective pattern diagram in which an internal configuration of a heat receiving part and a heat radiation part are seen through schematically.

[Fig. 7]

Fig. 7 is a side face perspective view showing a structure of